



TG-NSP35LV

Non-Silicone Thermal Putty

RoHS Compliant

Features

- Thermal Conductivity 3.5 W/mK
- Easily dispensable from manual, semi-automatic or fully automatic systems
- Full turn-key support from Infratron
- Low thermal impedance
- Low viscosity at room temperature
- Ultra-low compression forces
- High tack on most surfaces and reworkable
- Proven long term reliability

Applications

Consumer Electronics –Set-top boxes, IP routers, ECUs, Memory and Power modules

Standard Sizes

Syringe

30cc

55cc

Pot / Pail

0.45kg

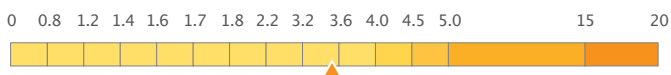
2.2kg

9kg

36kg

Properties

Thermal Conductivity : 3.5 W/mK



Properties	TG-NSP35LV	Unit	Test Method
Thermal Conductivity	3.5	W/mK	ASTM D5470
Viscosity @ 25°C	1,000,000	1 sec ⁻¹ , cPs	Rheometer
Viscosity @ 50°C	750,000	1 sec ⁻¹ , cPs	Rheometer
Colour	Grey	-	Visual
Flow Rate (30cc syringe, 50psi @ 25°C)	8	g/min	Infratron
Specific Gravity @ 25°C	2.7	-	ASTM D-70
Anticipated Minimum Bond Lines	150	µm	-
Operating Temperature Range	-40~+200	°C	Infratron
Bleed @ 200°C, 24 hours	<0.3	%/Wt	ASTM 6814-17
Evaporation @ 200°C, 24 hours	<0.1	%/Wt	ASTM 6814-17
Dielectric Strength, 1.27mm gap	>12	kV/mm	ASTM D-149
Dielectric Strength, 1.27mm gap after exposure to 85°C/85% R.H. for 48 hours	>8	kV/mm	ASTM D-149
Dielectric Constant 25°C @1,000 Hz	5.0	-	ASTM D-150
Dissipation Factor 25°C @1,000 Hz	0.0027	-	ASTM D-150
Volume Resistivity, ohm-cm	2.15 x 10 ⁵	ohm-cm	ASTM D-257
Shelf Life	60	months	Infratron